

Ref #	Hits	Search Query	DBs	Default Operator	Plurals	Time Stamp
L1	68265	(bond\$4 adj (agent or material or substance) or solder\$4 or adhesive or epoxy or glue) and ("tg" or "t. sub.g" or glass adj transition)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/02/09 15:24
L2	11705	1 and (deform\$4 or deformation)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/02/09 15:29
L3	7281	((228/173.1,173.2,180.1,180.22, 228,127) or (156/155,196,295,297, 380.5,380.8)).CCLS.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/02/09 15:26
L5	51	2 and 3	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/02/09 15:26
L6	5	5 and (deform\$4 or deformation) near (pcb or pwb or board or substrate)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/02/09 15:31
L7	15700	1 and (deform\$4 or deformation or embed\$5)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/02/09 15:29
L8	70	3 and 7	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/02/09 15:29
L9	5	8 and (deform\$4 or deformation) near (pcb or pwb or board or substrate)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/02/09 15:31

Ref #	Hits	Search Query	DBs	Default Operator	Plurals	Time Stamp
L1	68265	(bond\$4 adj (agent or material or substance) or solder\$4 or adhesive or epoxy or glue) and ("tg" or "t. sub.g" or glass adj transition)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/02/09 14:35
L2	11705	1 and (deform\$4 or deformation)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/02/09 14:36
L3	998	2 and (deform\$4 or deformation) near (revers\$6 or plastic\$6)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/02/09 15:04
L4	6	3 and ("tg" or "t.sub.g" or glass adj transition) near (pcb or pwb or board or substrate)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/02/09 14:37
L5	942	3 and (press\$4 or force or load)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/02/09 15:04
L6	6	4 and 5	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/02/09 14:58
L7	47	"6063649" or "5714252"	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/02/09 14:58
L8	23	3 and (deform\$4 or deformation) near (pcb or pwb or board or substrate)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/02/09 15:04

L9	23	8 and (press\$4 or force or load)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/02/09 15:04
----	----	-----------------------------------	-------------------------------------------------------------------	----	----	------------------